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HUANG et al.(10) **Pub. No.: US 2024/0237269 A1**(43) **Pub. Date: Jul. 11, 2024**(54) **COOLING PIPE AND COOLING ASSEMBLY
AND ELECTRONIC DEVICE INCLUDING
THE SAME****Publication Classification**(51) **Int. Cl.**
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Taipei City (TW)(57) **ABSTRACT**

A cooling assembly is configured for at least one electronic module. The cooling assembly includes at least one thermally conductive plate and at least one cooling pipe. The thermally conductive plate is configured to be attached on one surface of the electronic module. The cooling pipe is configured to be in thermal contact with one side of the thermally conductive plate located farther away from the electronic module. The cooling pipe comprises a pipe wall, and the pipe wall surrounds and forms a fluid channel. The pipe wall of the at least one cooling pipe has a thermally conductive characteristic, and the pipe wall of the at least one cooling pipe is elastically deformable in response to a pressure variation in the fluid channel.

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